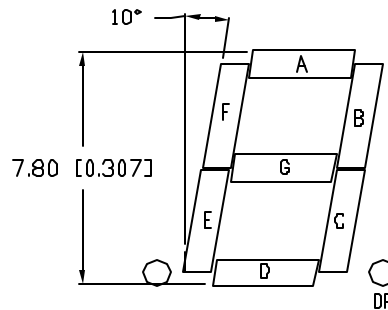
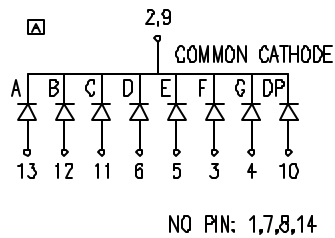
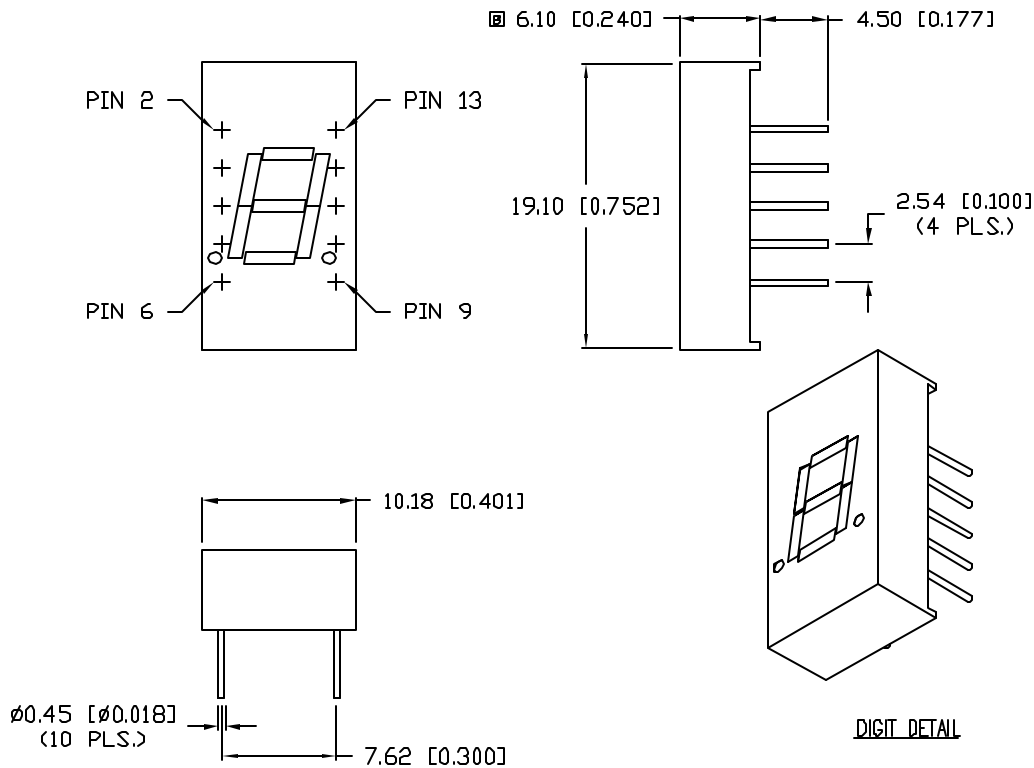


UNCONTROLLED DOCUMENT

PART NUMBER  
LDS-C304RI-SI

REV.  
B

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11153	7.21.04
B	E.C.N. #11193	12.07.04



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		636		nm	
FORWARD VOLTAGE		2.0	2.6	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_r=100\mu\text{A}$
AXIAL INTENSITY		13000		$\mu\text{cd}$	$I_f=10\text{mA}$
EMITTED COLOR:	RED				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT  $25^\circ\text{C}$  PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM $25^\circ\text{C}$	-1.6	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-30 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

\*  $t < 10\mu\text{s}$

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X= $\pm 1$  ( $\pm 0.039$ ), X.X= $\pm 0.5$  ( $\pm 0.020$ ), X.XX= $\pm 0.25$  ( $\pm 0.010$ ), X.XXX= $\pm 0.127$  ( $\pm 0.005$ ). LEAD SIZE= $\pm 0.05$  ( $\pm 0.002$ ), LEAD LENGTH= $\pm 0.75$  ( $\pm 0.030$ ), MIN= $\begin{matrix} +0.00 \\ -0.00 \end{matrix}$  DECIMAL PRECISION MAX.= $\begin{matrix} +0.00 \\ -0.00 \end{matrix}$  DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV. B	PART NUMBER LDS-C304RI-SI
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0.30" SEVEN SEGMENT, LED DISPLAY, COMMON CATHODE,  
636nm RED CHIPS, GRAY FACE WITH WHITE SEGMENTS.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 1.18.03
			PAGE: 1 OF 1
			SCALE: N/A